



A Perfect Match for Matchless Performance

Micron® Multichip Packages

Form Factor, Speed, Power. Choose All That Apply.

Form factor, speed, power—your mobile customers want all three. With Micron's MCPs, you can respond to customers' ever-increasing demands without compromising leading-edge performance. Mix and match devices, configurations, and package options and find the just-right combination of low power, high reliability, and overall robustness.

Small Form Factor

This is in for wireless and handheld consumer products. And your customers want ever-thinner and ever-sleeker designs for all their handheld electronics. Make your designs match with fully tested, stackable, chip-scale packaging solutions—available in Mobile LPDRAM, Mobile LPDRAM/NAND, and Mobile LPDRAM/NAND/e-MMC™ combinations.

Speed

Thin is nothing without performance and speed to match. No need to compromise because our industry-standard NAND Flash offers high-performance features, including a READ CACHE function that can be used to stream more than 30 MB/s, and our Mobile LPDRAM achieves data transfer rates of 400 Mb/s and delivers clock speeds of up to 200 MHz.

Low Power

Who wants a battery that can't hold a charge? Dramatically reduce power consumption and worry no more. Our Mobile LPDRAM devices with inherently low self refresh current are excellent battery-life extenders.

4 Reasons Why Micron's MCPs Are a Perfect Match

1. Technical Support

Streamline time-to-market with experienced, market-specialized design support.

2. Custom Software Support

Design with confidence knowing that we've anticipated the technical challenges and collaborated with chipset vendors and operation system engineers to solve them.

3. Compact Footprint

Enable ever-smaller and sleeker product designs with small footprints and low heights.

4. Broad Portfolio

Maximize feature set and functionality with Micron's comprehensive MCP portfolio.



NAND/Mobile LPDDR MCP

NAND Density	Bus Width	Mobile LPDDR Density	Secondary Bus Width	RoHS	Voltage	Package	Clock Rate	Temp Range
1Gb	x16	512Mb	x32	Yes	1.7V–1.9V	152-ball VFBGA	133–166 MHz	–40°C to +85°C
2Gb	x16	1Gb	x32	Yes	1.7V–1.9V	152-, 168-ball VFBGA	133–166 MHz	–40°C to +85°C
2Gb	x16	2Gb	x32	Yes	1.7V–1.9V	168-ball VFBGA	133–166 MHz	–40°C to +85°C
4Gb	x16	2Gb	x32	Yes	1.7V–1.9V	152-, 168-ball VFBGA	133–166 MHz	–40°C to +85°C

Mobile LPDDR2 PoP

Density	Bus Width	RoHS	Voltage	Clock Rate	Package	Temp Range
1Gb	x32	Yes	1.2V	333–533 MHz	168-ball PoP	–40°C to +85°C
2Gb	x32, x64	Yes	1.2V	333–400 MHz	168-, 216-, 240-ball PoP	–40°C to +85°C
4Gb	x64	Yes	1.2V	333–400 MHz	168-, 216-, 240-ball PoP	–40°C to +85°C
8Gb	x64	Yes	1.2V	333–400 MHz	216-, 240-ball PoP	–40°C to +85°C

Mobile LPDDR PoP

Density	Bus Width	RoHS	Voltage	Clock Rate	Package	Temp Range
512Mb	x32	Yes	1.8V	167 MHz	152-ball PoP	–40°C to +85°C
1Gb	x32	Yes	1.8V	167–200 MHz	152-, 168-ball PoP	–40°C to +85°C
2Gb	x32	Yes	1.8V	167–200 MHz	152-, 168-ball PoP	–40°C to +85°C
4Gb	x32	Yes	1.8V	167–200 MHz	152-, 168-, 240-ball PoP	–40°C to +85°C
8Gb	x32	Yes	1.8V	167–200 MHz	152-, 168-, 240-ball PoP	–40°C to +85°C

Get More from TI-OMAP Processors or Beagle Boards—with Micron MCPs

Our high-performance MCPs are validated by TI and Beagle Board and are optimized to work with OMAP35x application processors and Beagle Boards. So, if your designs use those products, our memory will help them perform to their fullest potential.

Contact Us

Whether you're trying to minimize power consumption, maximize board space, increase speed, or do everything at once, Micron's MCPs can drive your design no matter the application. Get more information on our Web site at www.micron.com/products/mcps.

micron.com

Products are warranted only to meet Micron's production data sheet specifications. Products and specifications are subject to change without notice.

Micron and the Micron logo are trademarks of Micron Technology, Inc. e-MMC is a trademark of the MultiMediaCard Association. All other trademarks are the property of their respective owners. ©2009 Micron Technology, Inc. All rights reserved.12/09 EN.L

